

ABSTRACT

The present invention pertains to a treatment solution for appropriately removing natural oxide films or organic substances present on the surface of copper or copper alloys. The present invention provides a chemical polishing solution used for surface treatment of copper or copper alloys, the chemical polishing solution containing, on the basis of the total amount of the chemical polishing solution, (A) 0.1-3.5 mass% of hydrogen peroxide, (B) 1-20 mass% of at least one selected from the group consisting of sulfuric acid and nitric acid, (C) 0.05-0.8 mass% of a fluoride in terms of fluorine atoms, (D) 0.01-1 mass% of at least one selected from the group consisting of anthranilic acid, cyclohexylamine, cyclohexanol, and 1,5-pentanediol, (E) 0.0005-0.005 mass% of a fluorine-based surfactant, and (F) water.